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| <b>Information Disclosure<br/>Statement By Applicant</b><br><br>(Use Several Sheets if Necessary) | Atty. Docket No.<br>NVIDP234/P000825                    | Application No.:<br>10/633,004     |
|   | Applicant:<br>Singh et al.<br>Filing Date:<br>7/31/2003 | Group Art Unit:<br>Unassigned 2811 |

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| Examiner HUNG VU |     | Date Considered 10/05/04  |

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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| <b>Form 1449 (Modified)</b><br><br><b>Information Disclosure<br/>Statement By Applicant</b><br><br>(Use Several Sheets if Necessary) | Atty. Docket No. | Application No.: |
|  | NVIDP234/P000825 | 10/633,004       |
|  | Applicant:       |                  |
|  | Singh et al.     |                  |
|  | Filing Date:     | Group Art Unit:  |
|  | 7/31/2003        | Unassigned 281   |

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|                  | MM  |            |            |                    |       |           |             |
|                  | NN  |            |            |                    |       |           |             |
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| Examiner HUNG VU |     | Date Considered 10/05/04   |

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